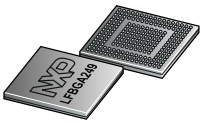


SOT1928-1

LFBGA249, plastic low profile fine-pitch ball grid array package; 249 balls; 12.0 mm x 12.0 mm x 1.30 mm body

9 April 2020 Package information

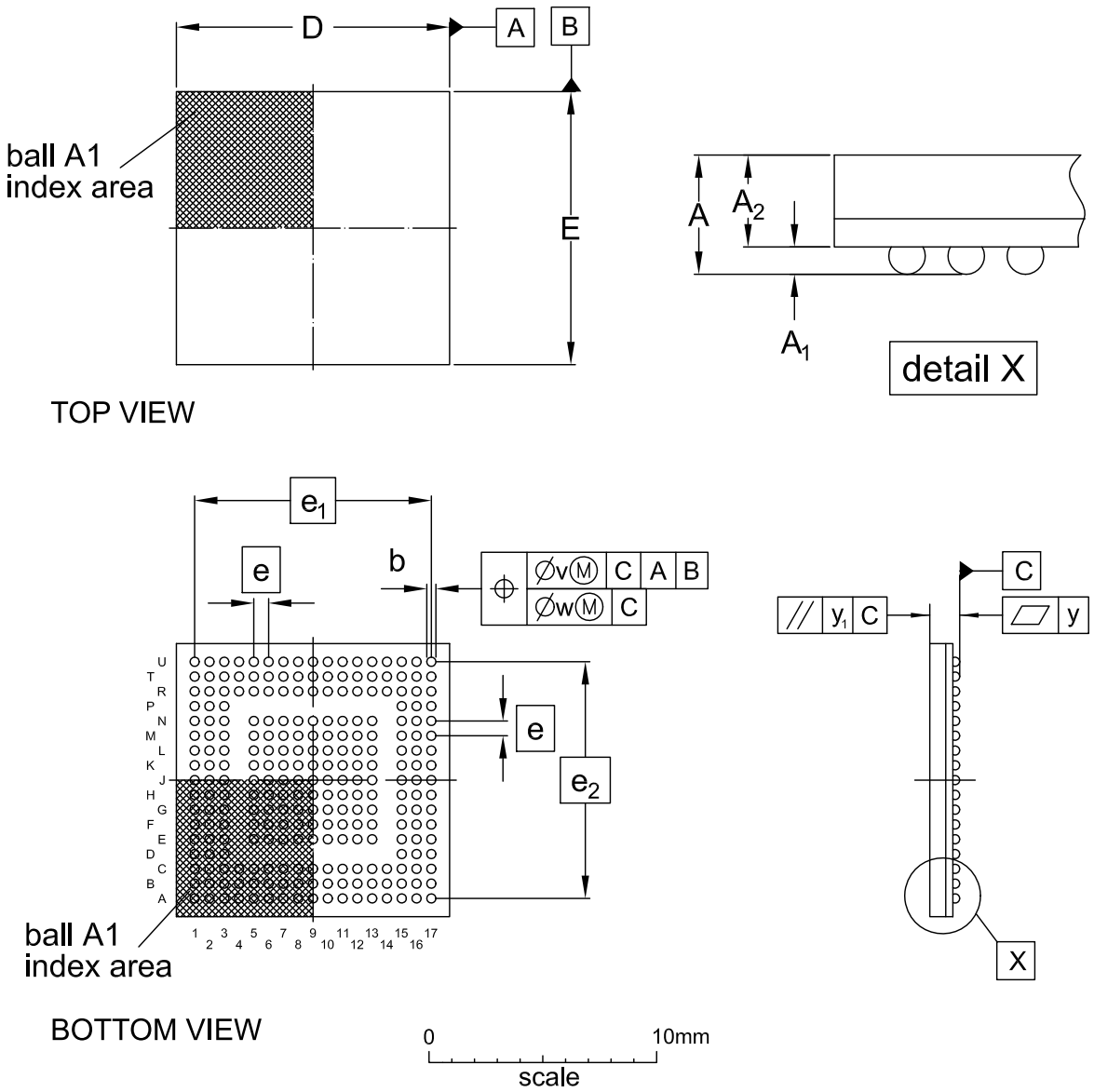
1 Package summary

Terminal position code	B (bottom)
Package type descriptive code	LFBGA249
Package style descriptive code	LFBGA (low profile fine-pitch ball grid array)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	25-03-2020
Manufacturer package code	SOT1928-1

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	11.9	12	12.1	mm
package width	11.9	12	12.1	mm
seated height	1.2	1.3	1.45	mm
package height	0.95	1	1.1	mm
nominal pitch	-	0.65	-	mm
actual quantity of termination	-	249	-	

2 Package outline



DIMENSIONS (mm are the original dimensions)

UNIT		A	A_1	A_2	b	D	E	e	e_1	e_2	v	w	y	y_1
mm	MAX.	1.45	0.35	1.10	0.45	12.1	12.1							
	NOM.	1.30	0.30	1.00	0.40	12.0	12.0	0.65	10.4	10.4	0.15	0.08	0.1	0.1
	MIN.	1.20	0.25	0.95	0.35	11.9	11.9							

Figure 1. Package outline drawing for LFBGA249 (SOT1928-1)

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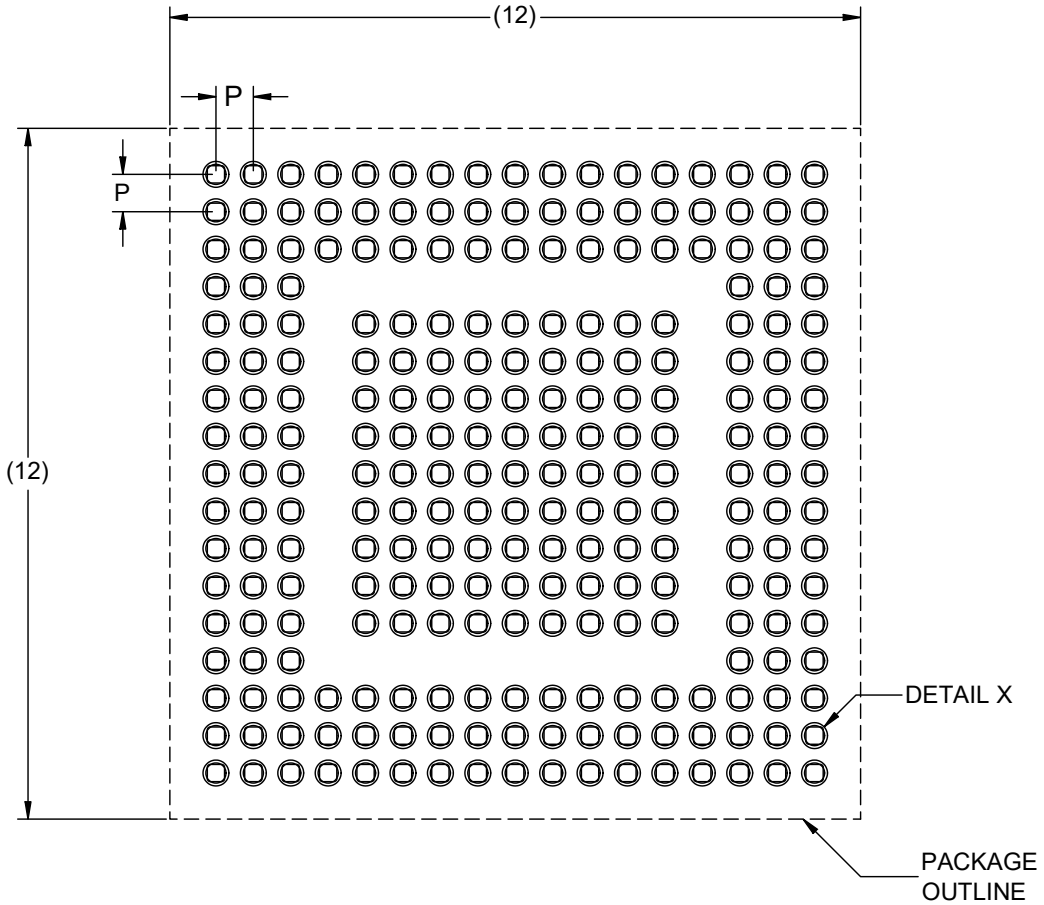
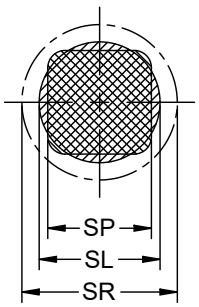
3 Soldering



solder land (SL)

solder paste deposit (SP)

—·— solder resist opening (SR)
– – – occupied area
Recommended stencil thickness 0.1 mm



detail X

Dimensions in mm

P	SL	SP	SR
0.65	0.35	0.30	0.45

Figure 2. Reflow soldering footprint for LFBGA249 (SOT1928-1)

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4 Legal information

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